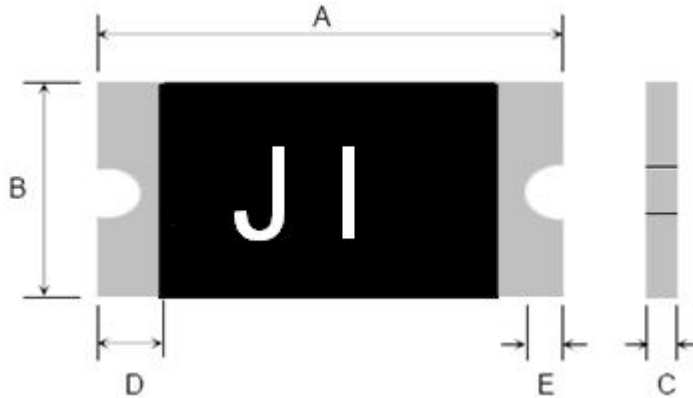


**JK-nSMD150-16PPTC DEVICES**

PartNumber : Q/JKTD-16-150



Terminal pad materials : Tin-Plated Nickle-copper

 Terminal pad solderability : Meets EIA specification  
 RS 186-9E and ANSI/J-STD-002 Category 3.

Marking : JI=1206(150)

Table1 :DIMENTION(Unit : mm)

Model	Marking	A		B		C		D	E
		Min.	Ma.	Min.	Max.	Min.	Max	Min.	Min.
JK-SMD1206-150	JI	3.00	3.50	1.50	1.80	0.60	1.50	0.15	0.10

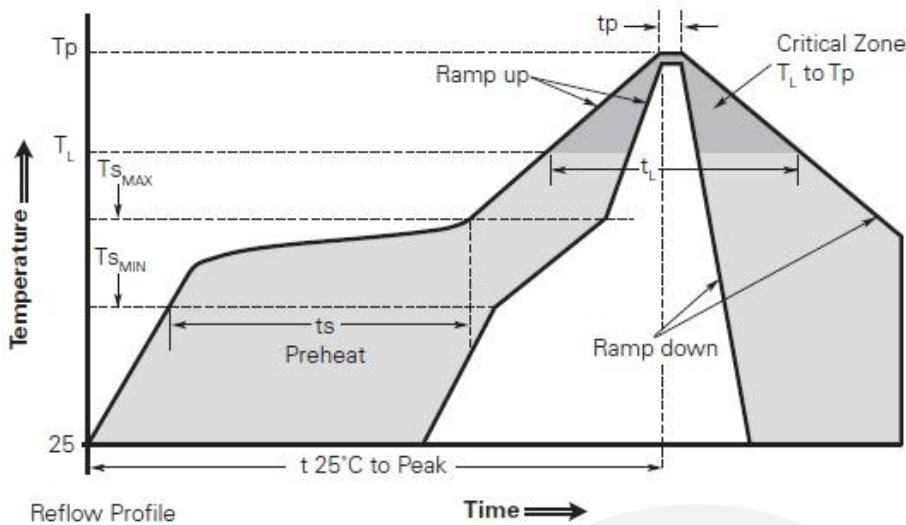
Table2 :PERFORMANCE RATINGS:

Model	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	I <sub>hold</sub> @25°C (A)	I <sub>trip</sub> @25°C (A)	P <sub>d</sub> Typ (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	R <sub>i</sub> min (Ω)	R <sub>l</sub> max (Ω)
JK-SMD1206-150	16.0	40	1.50	3.00	0.6	8.0	0.3S	0.040	0.150

Table3:Test Conditons and Standards

Item	Test Conditon	Standard
Initial Resistance	25°C	0.040~0.130Ω
I <sub>H</sub>	25°C, 1.50A, 60min	No Trip
T <sub>trip</sub>	25°C, 8.0A	≤0.3s
Trip endurance	16.0V, 40A, 1hr	No arcing or burning

**Operating Temperature: -40°C TO 85°C**
**Packaging: Bulk ,3500pcs per bag**

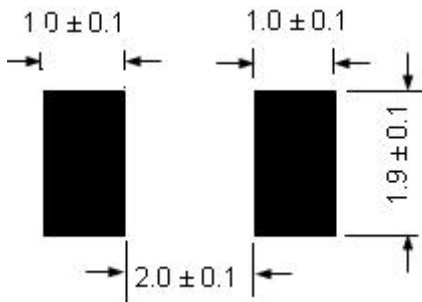
**Solder reflow conditions**


Profile Feature	Pb-Free Assembly
<b>Average ramp up rate (Ts<sub>MAX</sub> to Tp)</b>	3°C/second max.
<b>Preheat</b>	
• Temperature min. (Ts <sub>MIN</sub> )	150°C
• Temperature max. (Ts <sub>MAX</sub> )	200°C
• Time (ts <sub>MIN</sub> to ts <sub>MAX</sub> )	60-120 seconds
<b>Time maintained above:</b>	
• Temperature (T <sub>L</sub> )	217°C
• Time (t <sub>L</sub> )	60-150 seconds
<b>Peak/Classification temperature (Tp)</b>	260°C
<b>Time within 5°C of actual peak temperature</b>	
Time (tp)	30 seconds max.
<b>Ramp down rate</b>	3°C/second max.
<b>Time 25°C to peak temperature</b>	8 minutes max.

**Note:** All temperatures refer to topside of the package, measured on the package body surface.

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temperature profile meets RoHs leadfree process.

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

**Recommended pad layout (mm)**


**WARNING**

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage ( $L di/dt$ ) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

